

H150(LF)

特性/Features

Tg ≥ 150°C (DSC)

UV Blocking与 AOI兼容可提高PCB生产效率

UV Blocking and AOI compatible,
so as to increase production efficiency

优异的耐热性, Td ≥ 325°C, T288 ≥ 5min, 适合于无铅焊工艺;

High thermal performance, Td ≥ 325°C, T288 ≥ 5min,
suitable for lead-free process.

应用领域/Applications

计算机及外围设备、通讯设备、汽车电子。

Computer, communication equipment, automotive electronics.

主要特性/General properties

检测项目 Item	单位 Unit	检测条件 Test Condition	规范值 Spec	典型值 Typical Value	
玻璃化转变温度/Tg	°C	DSC	≥ 150	154.5	
剥离强度/1oz Peel Strength	N/mm	288°C, 10S	≥ 1.05	1.41	
热应力/Thermal stress	S	288°C, solder dip	> 10	180 s No delamination	
弯曲强度/Flexural Strength	N/mm ²	经向 LW 纬向 CW	≥ 415 ≥ 345	570 465	
燃烧性/Flammability	—	E 24/125	UL94V-0	V-0	
表面电阻/Surface Resistivity	MΩ	After moisture	≥ 1.0×10 ⁴	6.12×10 ⁷	
体积电阻/Volume Resistivity	MΩ·cm	After moisture	≥ 1.0×10 ⁹	6.25×10 ⁸	
介电常数/Dielectric Constant	—	1 MHz C 24/23/50	≤ 5.4	4.7	
介质损耗角正切/Loss Tangent	—	1 MHz C 24/23/50	≤ 0.035	0.016	
耐电弧/Arc Resistance	S	D48/50+D0.5/23	≥ 60	125	
击穿电压/Dielectric Breakdown	KV	D48/50+D0.5/23	≥ 40	57	
吸水率/Moisture Absorption	%	D24/23	≤ 0.35	0.10	
热分解温度/Td	°C	Weight Loss 5%	≥ 325	348	
CTE Z-axis	Alpha 1	ppm / °C	TMA	≤ 60	55
	Alpha 2	ppm / °C		≤ 300	276
	50 - 260 °C	%		≤ 3.5	3.3
T288	min	TMA	≥ 5	20	
相比漏电起痕指数/CTI	V	IEC-60112	175~250	200	

Specimen Thickness: 1.6mm; Specification sheet: IPC-4101D/99, is for your reference only

Explanation: C: Humidity conditioning; D: Immersion conditioning in distilled water;

E: Temperature conditioning;

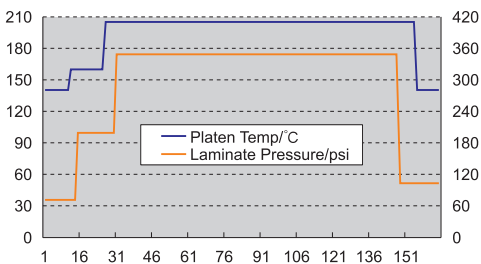
半固化片介绍-H150P(LF)

Prepreg instruction

H150P(LF) (UV Prepreg):

Prepreg Type	Resin Content(%)		压合厚度 / Cured Thickness			
	含量R/C(%)	公差Tolerance	Nominal		Range(±)mil	
	%	±	mm	mil	mm	mil
7628HRC	52	2	0.231	9.09	0.022	0.85
	50	2	0.22	8.66	0.022	0.85
	48	2	0.21	8.27	0.020	0.8
7628	45	2	0.195	7.68	0.019	0.75
	43	2	0.186	7.32	0.018	0.7
1506	48	2	0.164	6.46	0.017	0.65
	45	2	0.153	6.02	0.015	0.6
2116	58	2	0.136	5.35	0.014	0.55
	57	2	0.132	5.20	0.013	0.5
	55	2	0.125	4.92	0.013	0.5
	53	2	0.119	4.69	0.011	0.45
	50	2	0.11	4.33	0.011	0.45
1080	68	2	0.086	3.39	0.008	0.3
	65	2	0.077	3.03	0.008	0.3
	63	2	0.073	2.87	0.008	0.3

建议压制程式：Suggest cycle



Heat-up rate: 1.5~2.5°C/min (80~140°C)

Curing time: >60min (>180°C)

The hot pressing parameters is for your reference only, please turn to Zhejiang Huazheng New Material.Co.,Ltd for detailed information.

储存条件：

温度≤23°C、湿度≤50%，保存时间3个月；
温度≤5°C、密封条件下，保存时间6个月。

Storage Condition:

T≤23°C & ≤50%RH, Within 3 months;
T≤5°C Within 6 months (seal condition)

在上述要求内，我司可立即安排PP送样；
若有特殊要求，由供需双方商定。

Follow above condition, our company will arrange sample immediately. We can discuss if you have any special requirement.